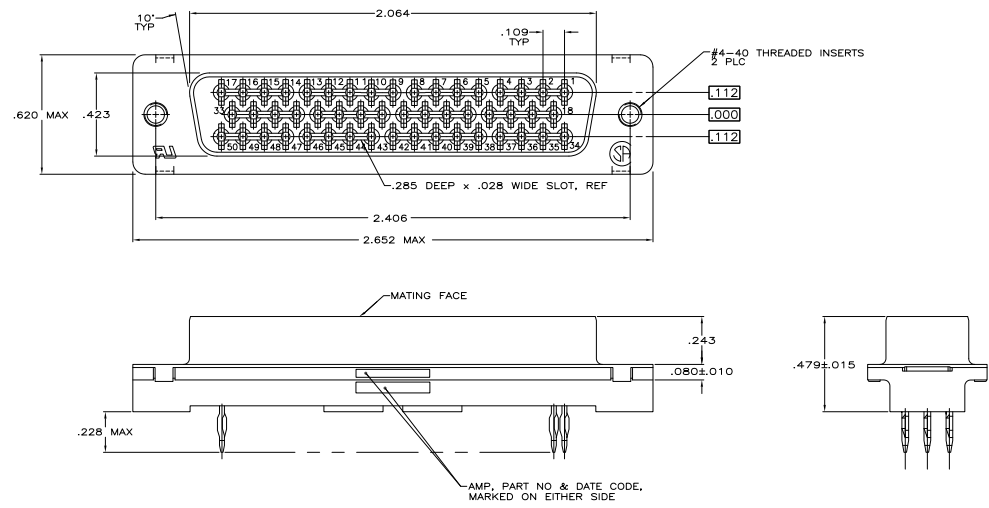


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REV	DATE	DESCRIPTION	BY	APP'D
00				
M		REVISED PER EDD-12-00090		



- △ FOR USE WITH .093 MINIMUM THICK PRINTED CIRCUIT BOARD. REFER TO APPLICATION SPECIFICATION FOR PRINTED CIRCUIT BOARD LAYOUT DIMENSIONS AND FINISH RECOMMENDATIONS.
- △ DUPLEX PLATED: GOLD FLASH ON MATING SURFACE, BRIGHT TIN OR BRIGHT TIN LEAD ON COMPLIANT PIN, ALL OVER NICKEL.
- △ .00030 MINIMUM GOLD IN MATING AREA.
 .000100 MINIMUM TIN OR TIN-LEAD ON COMPLIANT PIN.
 ALL OVER .000050 MINIMUM NICKEL.
 OR
 GOLD FLASH OVER PALLADIUM NICKEL.
 .00030 MINIMUM TOTAL IN MATING AREA.
 .000100 MINIMUM TIN OR TIN-LEAD ON COMPLIANT PIN.
 ALL OVER .000050 MINIMUM NICKEL.
- △ PLATED .0002-.0004 BRIGHT TIN

OBSOLETE	FULL	△	747144-3
	HALF	△	747144-2
OBSOLETE	HALF	△	747144-1

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REVISIONS: 04-28-11

TE Connectivity

RCPT ASSY, SIZE 5, 50 POSN, AMPLIMITE
 HOP, MOM PROFILE, W/ ACTION PIN CONT &
 METAL SHELL

108-40014
 114-40026

SIZE: A1 | DATE: 00779 | DRAWING NO: 747144

CUSTOMER DRAWING